BCMA Series

Common Moda Filters For Automotive Signal Line
Size 1210

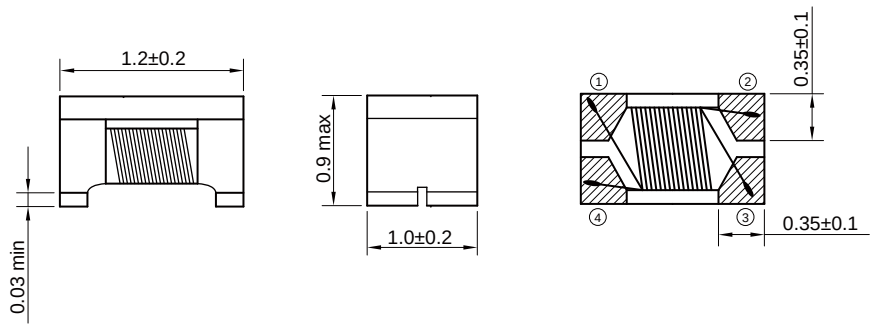
FEATURES

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- Common mode filters for Signal Line
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- Compliant with AEC-Q200
- Quan ty: 3000pcs

APPLICATION

- interfaces (MOST, IDB-1394, etc.)

Dimensions: [mm]



Land Pattern: [mm]

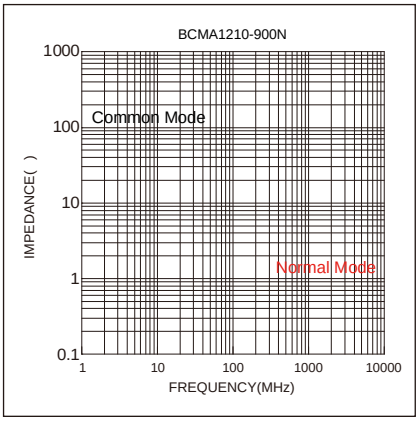


Electrical Properties:

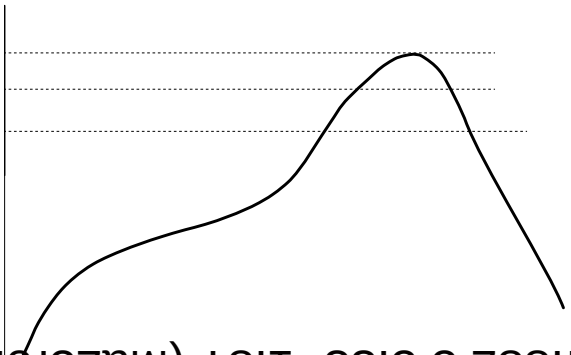
Part No	Z @ 100 MHz	Tol	I_R	R_{DC} Max.	Rated Volt. (V	IR Min.
BCMA1210-900N	90		200	0.40	50	10M

I_R refering to 20K self-hea ng above ambient temperature

Typical Electrical Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~180 sec.

Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

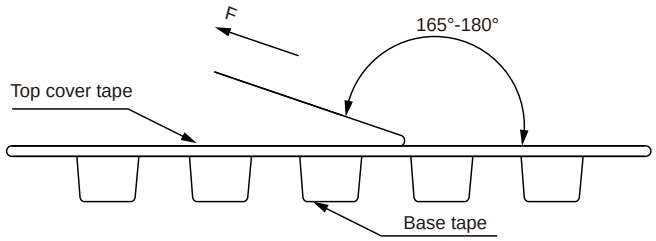
Allowed Reflow time: 3x max.

Packaging Information:

Tape Dimension:

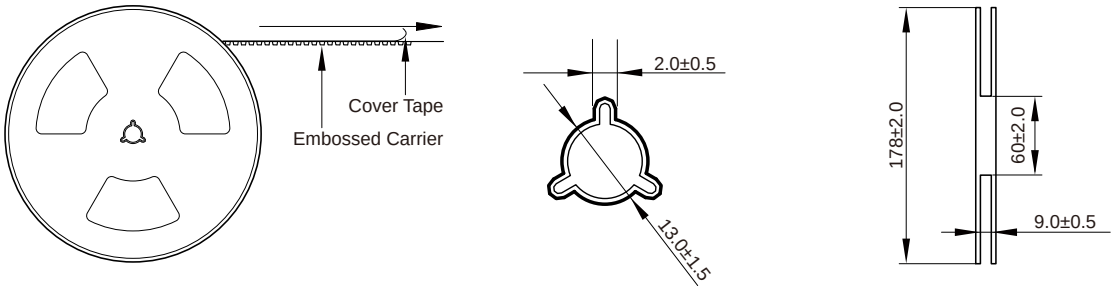
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
BCMA1210	1.12 ± 0.1	1.40 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	4.0 ± 0.1	8.0 ± 0.3	1.05 ± 0.1	1.75 ± 0.1	0.22 ± 0.05

Peel force of top cover tape:

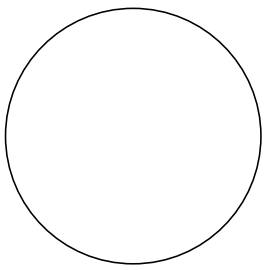


The peel force of top cover tape shall be between 0.15 to 0.78 N

Reel Dimension：[mm]



Packaging Quantity:



3000 Pcs/Reel

5 Reel /Inner box(15K Pcs)

8 Inner box/Carton box(120K Pcs)

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- 7.75
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